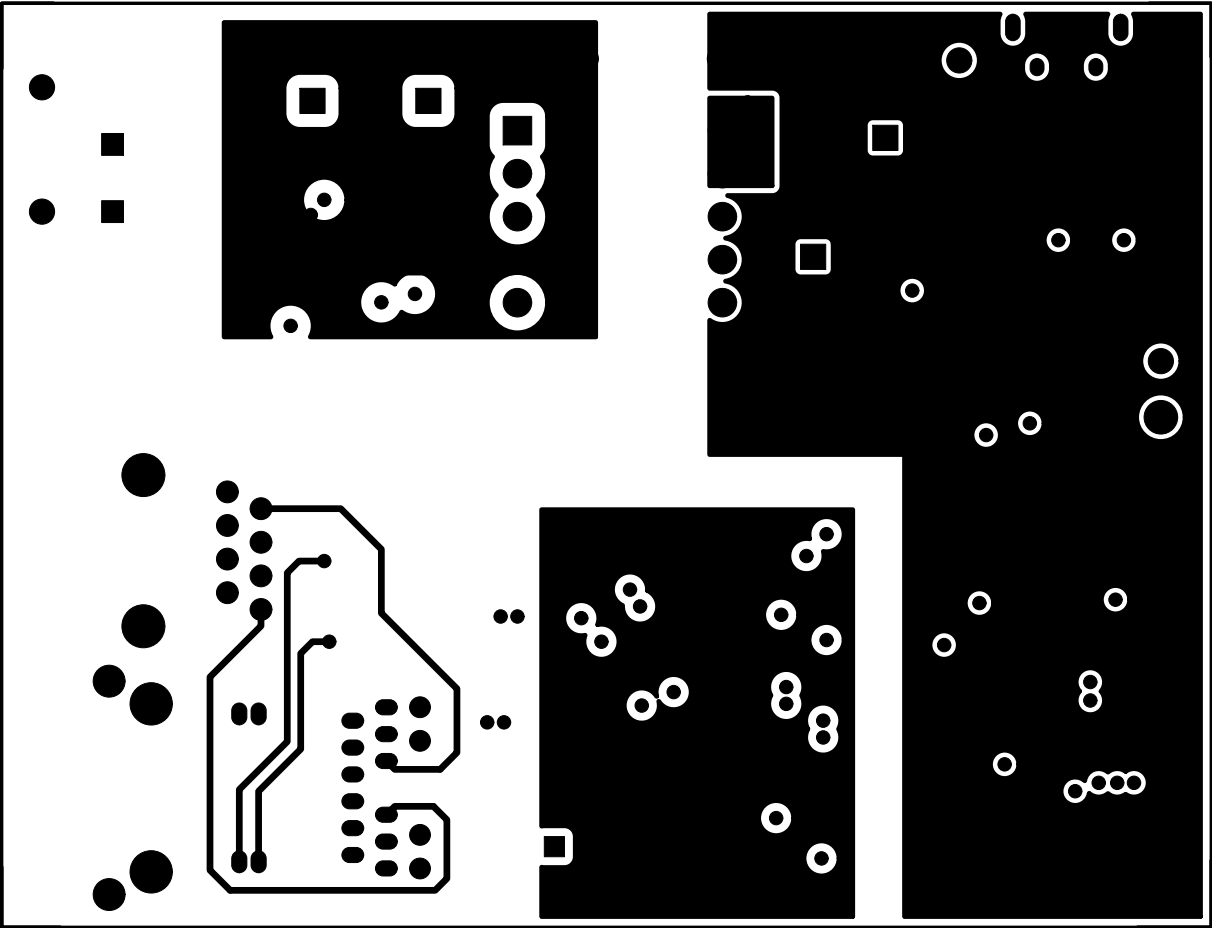
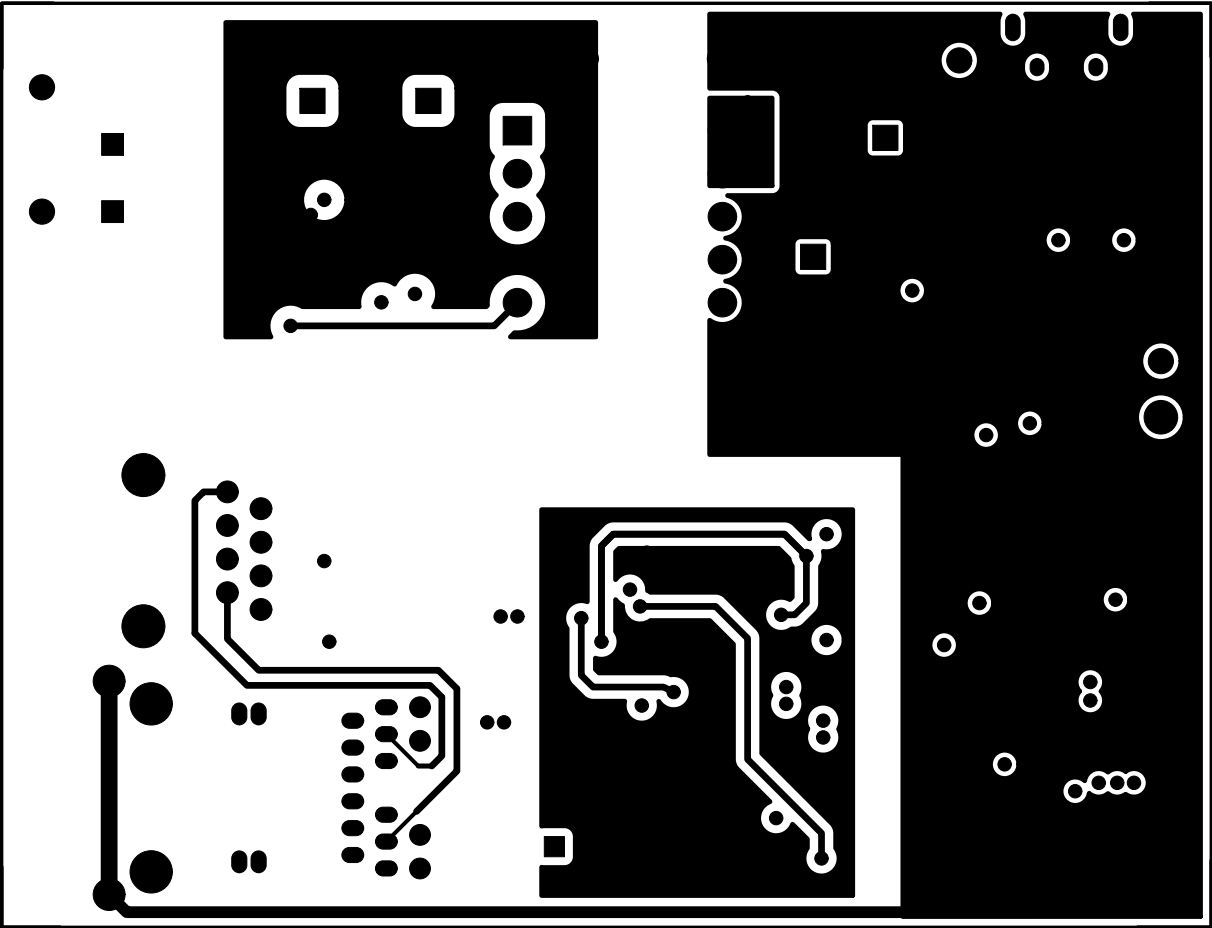


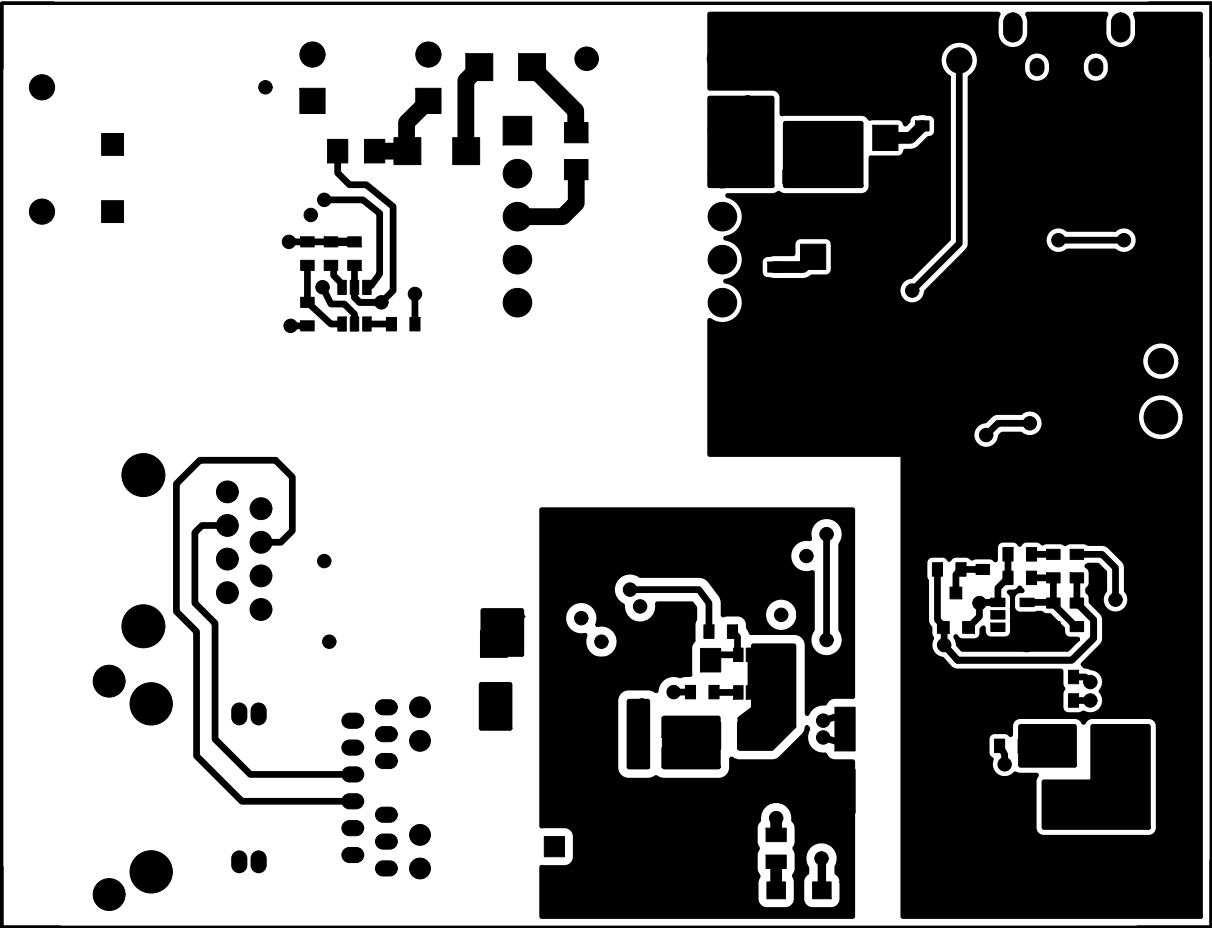
TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	{Project Number}	Rev.	A	L1									
Date:	{Start Date}	Filename:	PMP8455A.PCB	Engineer:	D.STRASSER	PCB Dsgnr:	R.SMITH	Modified Date:	{Modification Date}			Software	PADs v9.3



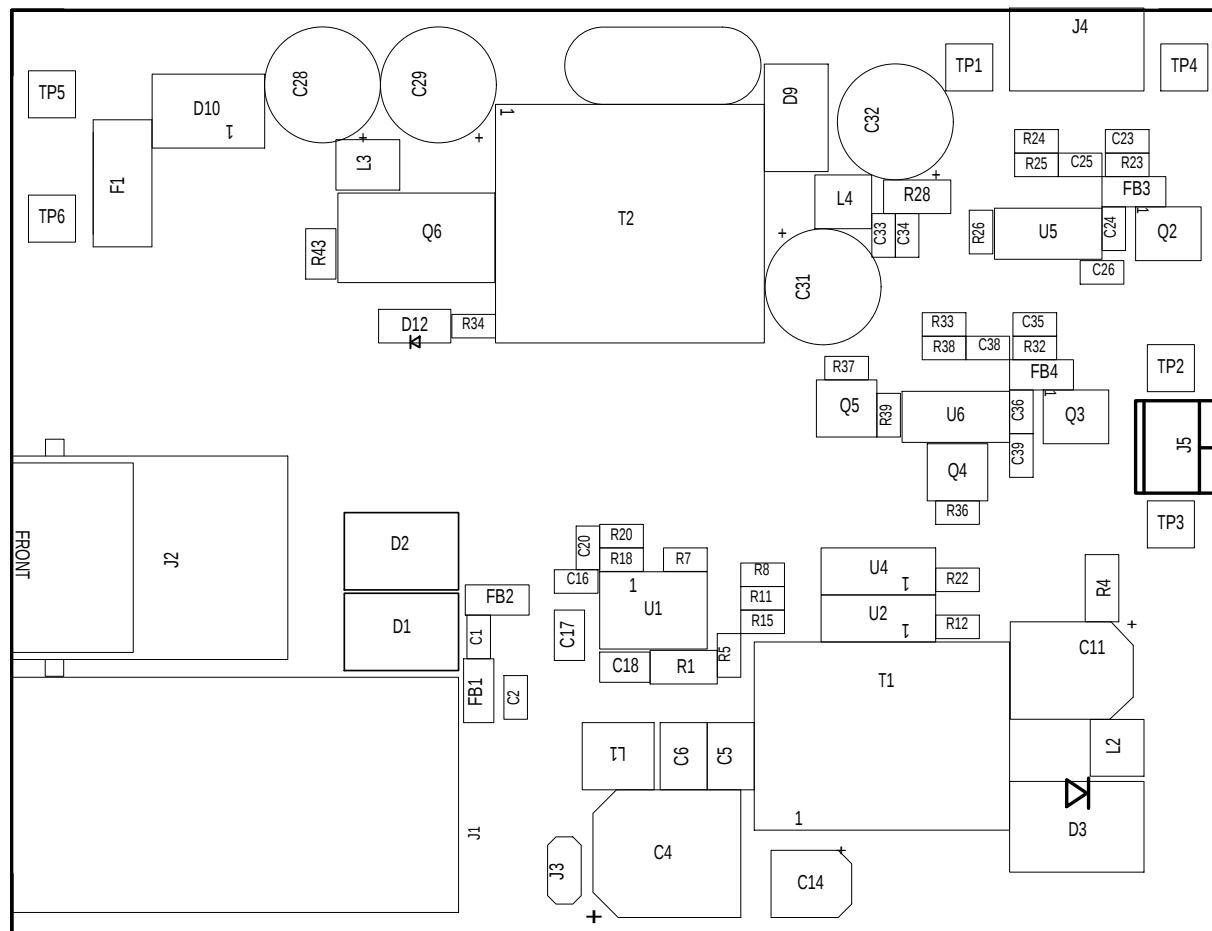
TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. {Project Number}		Rev. A		L2										
Date: {Start Date}	Filename: PMP8455A.PCB	Engineer: D.STRASSER	PCB Dsgnr: R.SMITH		Modified Date: {Modification Date}						Software PADS v9.3			



TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. {Project Number}		Rev. A			L3									
Date: {Start Date}	Filename: PMP8455A.PCB	Engineer: D.STRASSER	PCB Dsgnr: R.SMITH		Modified Date: {Modification Date}						Software PADs v9.3			

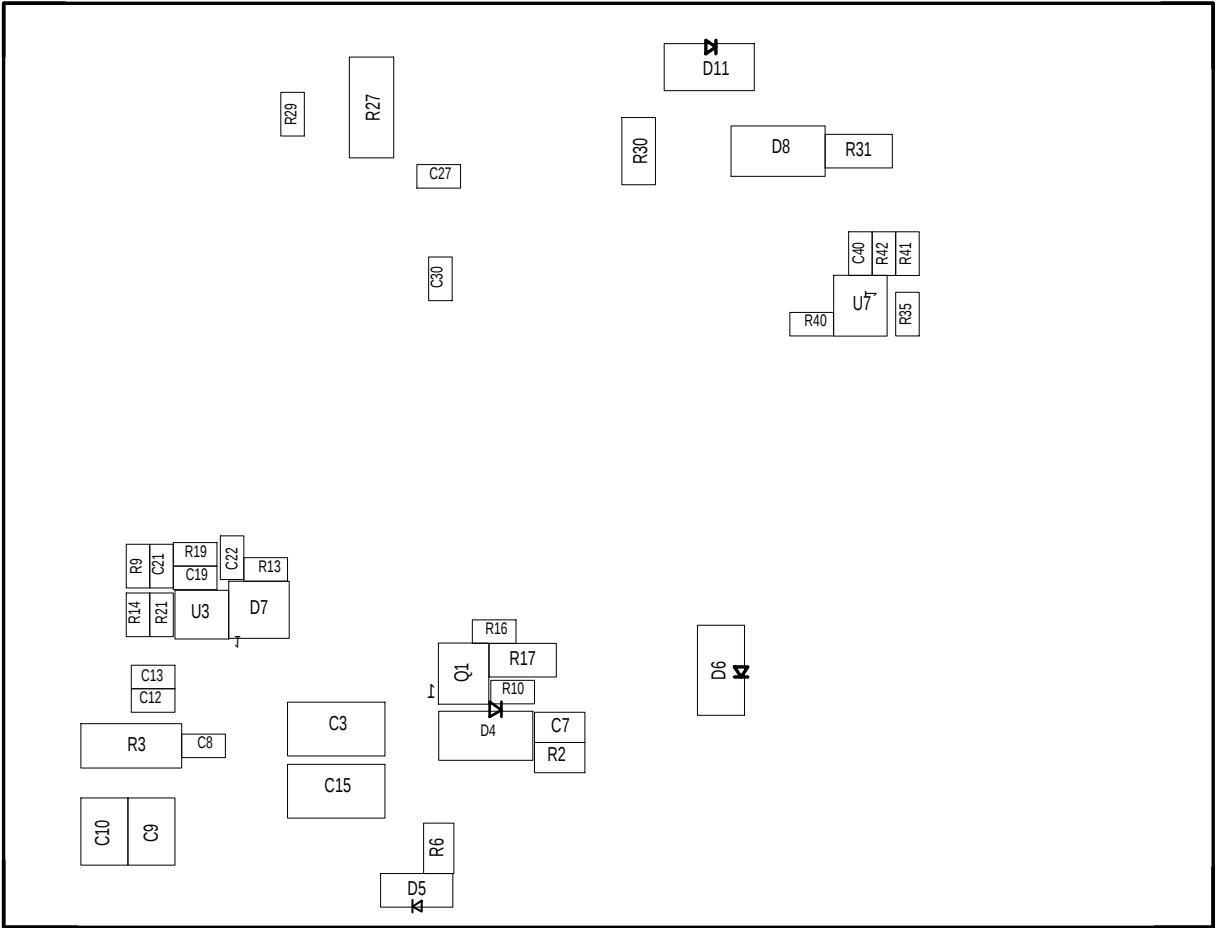


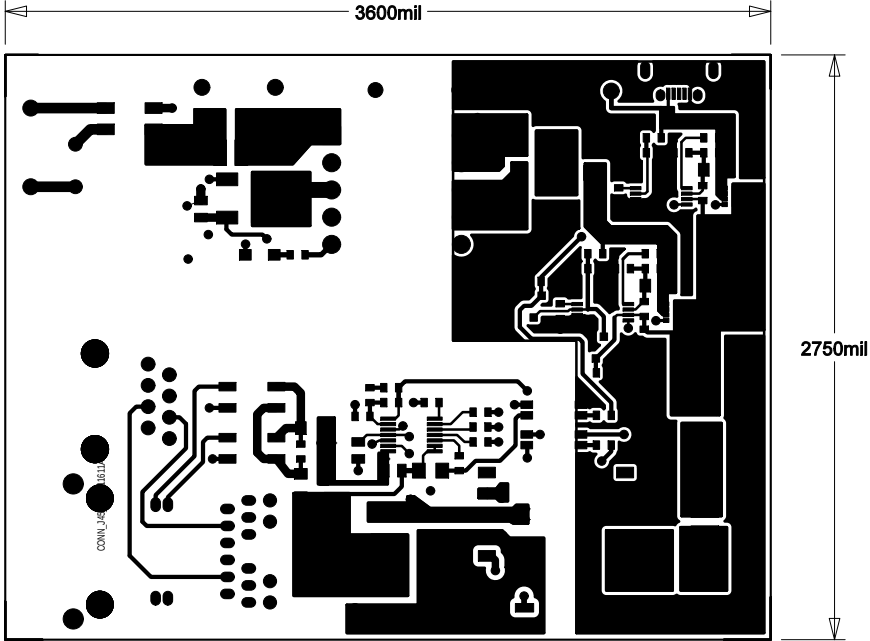
TEXAS INSTRUMENTS			Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
			Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. {Project Number}		Rev. A			L4									
Date: {Start Date}	Filename: PMP8455A.PCB	Engineer: D.STRASSER	PCB Dsgnr: R.SMITH		Modified Date: {Modification Date}						Software PADs v9.3			



TEXAS INSTRUMENTS				Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
				Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	Top	
Board No. {Project Number}				Rev. A		L1								TA	
Date: {Start Date}		Filename: PMP8455A.PCB		Engineer: D.STRASSER		PCB Dsgnr: R.SMITH		Modified Date: {Modification Date}						Software PADS v9.3	

{Start Date}		Filename: PMP8452A.PCB	Engineer: D.STRAESSER	PCB Design: R.SMITH	Modified Date: {Modification Date}		Software: PADS v8.3	
{Project Number}		Rev. A	Copper Layer Name					
Board No.			Top	Internal	Bot	2 Mask	P Mask	Assemble
								Dr





TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Drill Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No: {Project Number}		Rev: A	L1										FB
Date: (Start Date)	Filename: PMP8455A.PCB	Engineer: D.STRASSER		PCB Dsgnr: R.SMITH		Modified Date: (Modification Date)					Software: PADs v9.3		

FABRICATION CHART				
FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT	
			EXTERNAL	INTERNAL
<input type="checkbox"/> 0.031 <input checked="" type="checkbox"/> 0.062 <input type="checkbox"/> 0.093 <input type="checkbox"/> 0.125	<input checked="" type="checkbox"/> LAYER 1 <input checked="" type="checkbox"/> LAYER 4 <input type="checkbox"/> NONE	<input checked="" type="checkbox"/> LAYER 1 <input checked="" type="checkbox"/> LAYER 4 <input type="checkbox"/> NONE	<input type="checkbox"/> 1 OZ. <input checked="" type="checkbox"/> 2 OZ. <input type="checkbox"/> OTHER _____	<input type="checkbox"/> 1 OZ. <input checked="" type="checkbox"/> 2 OZ. <input type="checkbox"/> OTHER _____
DESIGN	TRACE/GAP SPACING		LAYER COUNT	
<input type="checkbox"/> SMD <input type="checkbox"/> THRU-HOLE <input checked="" type="checkbox"/> MIX	<input type="checkbox"/> 0.010/0.010 <input checked="" type="checkbox"/> 0.008/0.007 <input type="checkbox"/> 0.006/0.006		<input type="checkbox"/> SINGLE SIDED <input checked="" type="checkbox"/> 4 LAYER <input type="checkbox"/> 8 LAYER <input type="checkbox"/> OTHER _____	<input type="checkbox"/> 2 LAYER <input type="checkbox"/> 6 LAYER <input type="checkbox"/> 10 LAYER

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL:

ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
2. BASE LAMINATE:

PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM DECOMPOSITION TEMP (Td) OF 320 Deg c.

GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 4 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK:

SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT.
4. TOLERANCES:

UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.
5. PLATING:

HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
6. FINISH:

PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS

AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
7. LEGEND:

IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
8. MARKINGS:

BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
9. WORKMANSHIP:

BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
10. DOCUMENTATION:

PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
11. DRILL SIZES:

HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
12. PANEL BORDER:

ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
13. PROCESS CHANGES:

NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.

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